

Title (en)
POWER SEMICONDUCTOR MODULE AND METHOD FOR PRODUCING A SINTERED POWER SEMICONDUCTOR MODULE HAVING A TEMPERATURE SENSOR

Title (de)
LEISTUNGSHALBLEITERMODUL UND VERFAHREN ZUR HERSTELLUNG EINES GESINTERTEN LEISTUNGSHALBLEITERMODULS MIT TEMPERATURFÜHLER

Title (fr)
MODULE À SEMI-CONDUCTEURS DE PUISSANCE ET PROCÉDÉ DE FABRICATION D'UN MODULE À SEMI-CONDUCTEURS DE PUISSANCE FRITTÉ COMPORTANT UNE SONDE DE TEMPÉRATURE

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Application
EP 11810558 A 20111028

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Abstract (en)
[origin: WO2012062274A2] The invention relates to a method for producing electrical components that can be sintered, for jointly sintering with active components, wherein the components having a planar shape are provided with at least one flat lower face intended to be sintered, and an electrical contact area on the surface opposite the sintering surface is present in the form of a metal contact surface, which can be contacted at the top face by a common method from the following group: wire bonding or soldering or sintering or pressure contacting, wherein the component is a temperature sensor, on the lower face of which a metallization that can be sintered is provided on a ceramic body and on the ceramic body of which two electrical contact surfaces are provided for continuative electrical connection.

IPC 8 full level
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CPC (source: EP US)
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